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# Single N-Channel 1.5 V Specified PowerTrench<sup>®</sup> MOSFET 20 V, 9.5 A, 23 m $\Omega$

#### Features

- Max r<sub>DS(on)</sub> = 23 mΩ at V<sub>GS</sub> = 4.5 V, I<sub>D</sub> = 9.5 A
- Max r<sub>DS(on)</sub> = 29 mΩ at V<sub>GS</sub> = 2.5 V, I<sub>D</sub> = 8.0 A
- Max  $r_{DS(on)}$  = 36 m $\Omega$  at V<sub>GS</sub> = 1.8 V, I<sub>D</sub> = 4.0 A
- Max r<sub>DS(on)</sub> = 50 mΩ at V<sub>GS</sub> = 1.5 V, I<sub>D</sub> = 2.0 A
- HBM ESD protection level > 2.5 kV (Note 3)
- Low Profile-0.8 mm maximum in the new package MicroFET 2x2 mm
- Free from halogenated compounds and antimony oxides
- RoHS Compliant

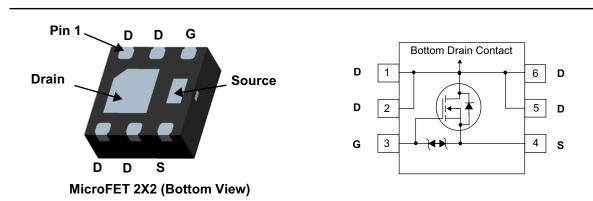


### **General Description**

This Single N-Channel MOSFET has been designed using Fairchild Semiconductor's advanced Power Trench process to optimize the  $r_{\rm DS(ON)}$  @ V\_{\rm GS} = 1.5 V on special MicroFET leadframe.

#### Applications

- Li-lon Battery Pack
- Baseband Switch
- Load Switch
- DC-DC Conversion



### MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Param		Ratings	Units		
V <sub>DS</sub>	Drain to Source Voltage			20	V	
V <sub>GS</sub>	Gate to Source Voltage		±8	V		
1	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	9.5		
D	-Pulsed		24	— A		
D	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.4	W	
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1b)	0.9		
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera		-55 to +150	°C		

### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	52	°C/M
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	145	°C/W

#### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
410	FDMA410NZ	MicroFET 2X2	7 "	8 mm	3000 units

June 2014

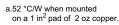
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25 °C		17		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0 V			1	μA
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±8 V, V <sub>DS</sub> = 0 V			±10	μA
On Chara	octeristics					
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$	0.4	0.7	1.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_{J}}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25 °C		-3		mV/°C
		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 9.5 A		17	23	mΩ
		$V_{GS}$ = 2.5 V, I <sub>D</sub> = 8.0 A		20	29	
r	Static Drain to Source On Resistance	V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 4.0 A		24	36	
r <sub>DS(on)</sub>		V <sub>GS</sub> = 1.5 V, I <sub>D</sub> = 2.0 A		29	50	
		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 9.5 A, T <sub>J</sub> = 125 °C		23	32	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 5 V, I <sub>D</sub> = 9.5 A		35		S
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance			815	1080	pF
C <sub>oss</sub>	Output Capacitance	— V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, — f = 1 MHz		130	175	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			85	130	pF
R <sub>g</sub>	Gate Resistance	f = 1 MHz		2.1		Ω
Switching	g Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time			7.5	15	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 9.5 A,		3.9	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 4.5 \text{ V}, \text{ R}_{GEN} = 6 \Omega$		27	44	ns
t <sub>f</sub>	Fall Time			3.7	10	ns
Q <sub>g</sub>	Total Gate Charge			10	14	nC
Q <sub>gs</sub>	Gate to Source Charge	── V <sub>GS</sub> = 4.5 V , V <sub>DD</sub> = 10 V, ── I <sub>D</sub> = 9.5 A		1.2		nC
ys				1	1	1

I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				2.0	A
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 2.0 A (Note 2)		0.7	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	-I <sub>F</sub> = 9.5 A, di/dt = 100 A/μs		12	22	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$_{\rm F}^{\rm TF} = 3.3 \text{ A}, \text{ div}\text{dt} = 100 \text{ A/}\text{\mu}\text{s}$		2.6	10	nC

NOTES:

1.  $R_{0,JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{0,JC}$  is guaranteed by design while  $R_{0,JA}$  is determined by the user's board design.

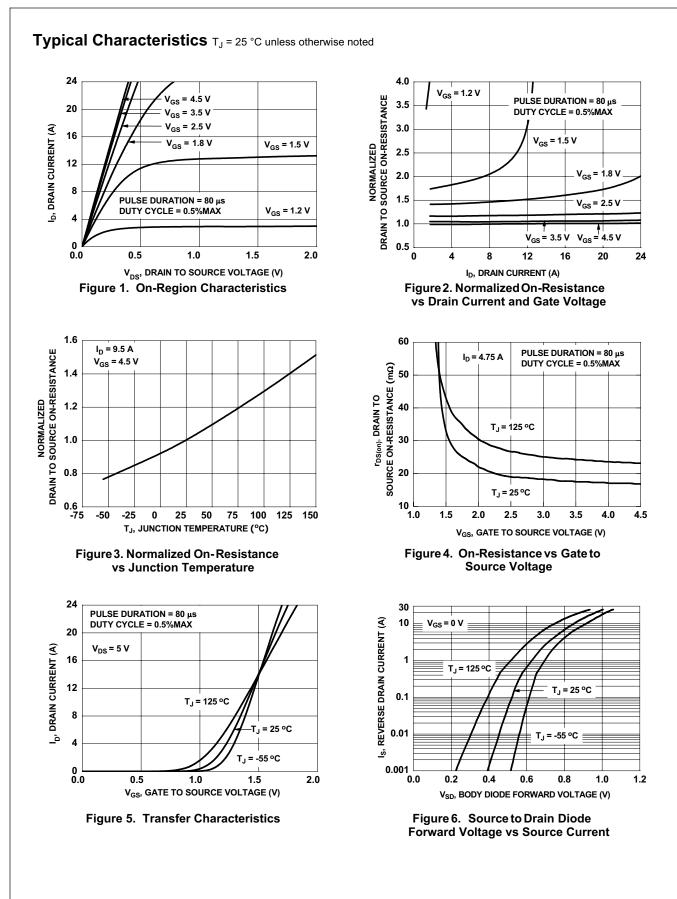




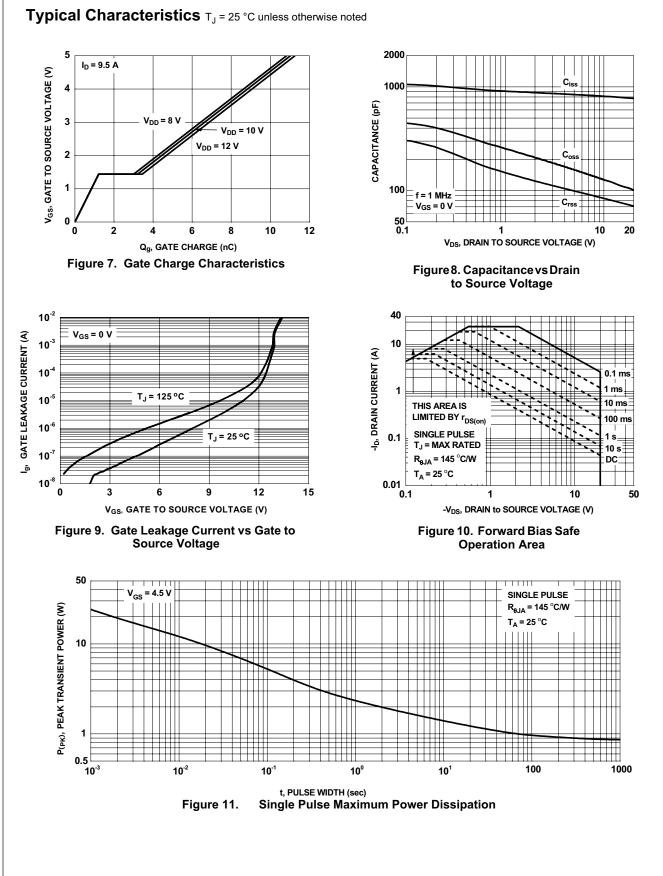


b. 145 °C/W when mounted on a minimum pad of 2 oz copper.

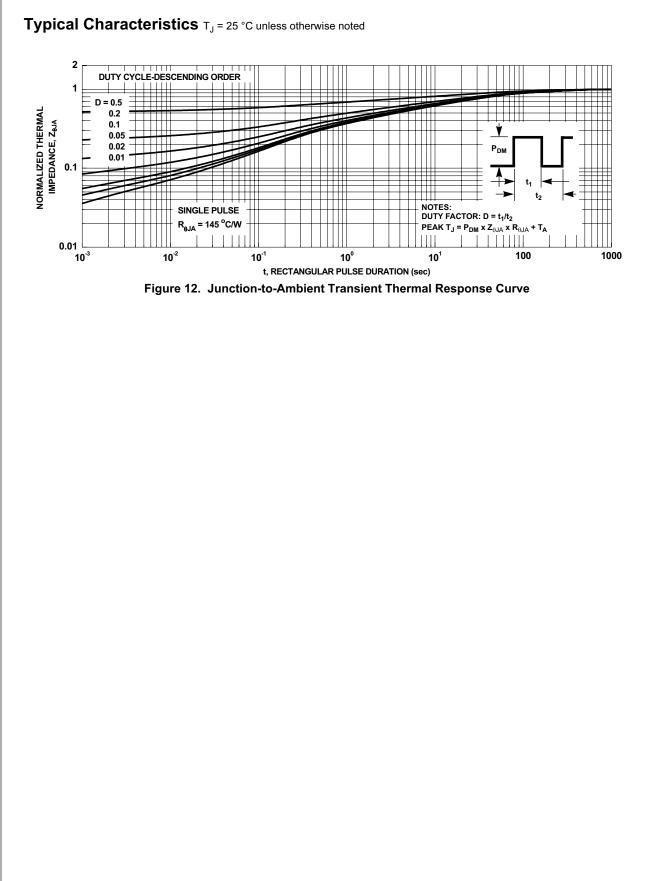
Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.</li>
The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

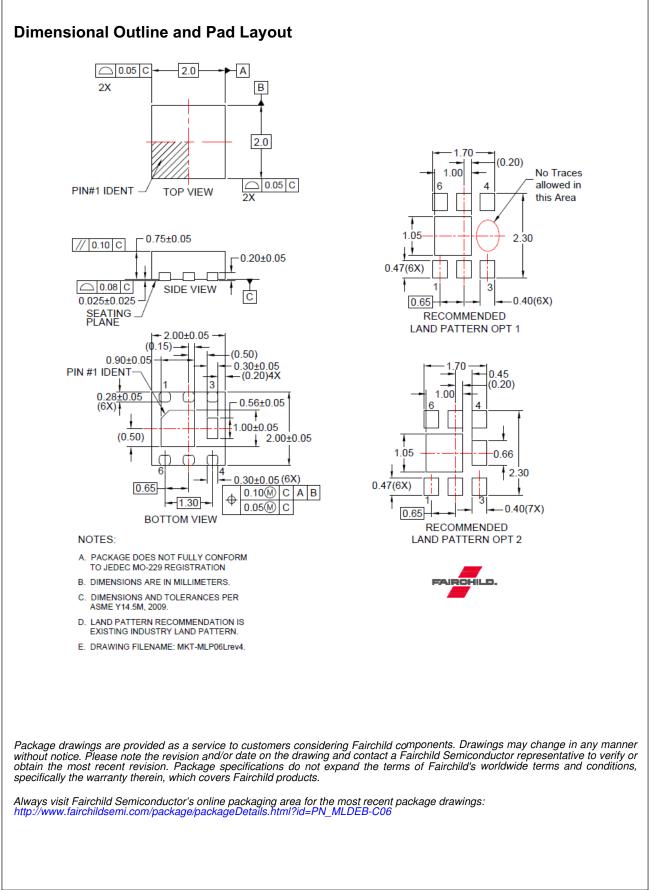


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FDMA410NZ Single N-Channel 1.5 V Specified PowerTrench® MOSFET





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Ī	Datasheet Identification	Product Status	Definition
	Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
	Preliminary First Production		Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
	No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
	Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.
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